

Tra-Con Tra-Bond 933-2 Moisture Resistant Chip Encapsulant

Category : Polymer , Thermoset , Epoxy , Filled/Reinforced Thermoset

Material Notes:

TRA-BOND 933-2 one component, highly filled, electrically insulating epoxy encapsulant is designed for encapsulating microelectronic chips. This epoxy provides excellent environmental and mechanical protection. TRA-BOND 933-2 encapsulant exhibits a longer work life and a lower moisture sensitivity than the anhydride-cured systems. The low coefficient of thermal expansion minimizes stress effects on components and wiring during thermal shock tests. Information provided by Tra-Con Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Tra-Con-Tra-Bond-933-2-Moisture-Resistant-Chip-Encapsulant.php

Physical Properties	Metric	English	Comments
Specific Gravity	2.20 g/cc	2.20 g/cc	Cured
Viscosity	50000 cP @Temperature 25.0 °C	50000 cP @Temperature 77.0 °F	Mixed (cp #51, 5 rpm)

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	92	92	
Adhesive Bond Strength	17.2 MPa	2500 psi	Lap shear, alum to alum, 2 hrs @ 150°C

Thermal Properties	Metric	English	Comments
CTE, linear	30.0 µm/m-°C	16.7 µin/in-°F	Below Tg
	120 µm/m-°C	66.7 µin/in-°F	Above Tg
Maximum Service Temperature, Air	150 °C	302 °F	
Minimum Service Temperature, Air	-60.0 °C	-76.0 °F	
Glass Transition Temp, Tg	120 °C	248 °F	Ultimate Tg

Processing Properties	Metric	English	Comments
Cure Time	15.0 min @Temperature 170 °C	0.250 hour @Temperature 338 °F	
	30.0 min @Temperature 150 °C	0.500 hour @Temperature 302 °F	
	60.0 - 120 min @Temperature 125 °C	1.00 - 2.00 hour @Temperature 257 °F	

Descriptive Properties	Value	Comments
Color	Black	
Working Life, months	2	At 25°C

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China